

separation is theoretically again possible, but is associated with high costs, low throughput and susceptibility to errors.

Embodiments of the present invention provide a device and a method for bonding two substrates, with which the bonding accuracy, in particular over the entire area, is increased.

All combinations of at least two features given in the description, in the claims and/or the drawings also fall within the scope of the invention. In stated value ranges, values lying inside the stated limits are also deemed to be disclosed as limiting values and can be claimed in any combination.

According to an embodiment of the invention, a method is proposed for bonding a first substrate with a second substrate at mutually facing contact faces of the substrates with the following steps, in particular the following sequence:

- holding of the first substrate to a first holding surface of a first holding device and holding of the second substrate to a second holding surface of a second holding device,
- fixing of the substrates at the holding surfaces by fixing elements,
- curvature of at least one of the contact faces before the contacting of the contact faces,
wherein,
after the contacting, only those fixing elements are at first switched off which are arranged uniaxially along a single contacting axis, and the remaining fixing elements remain switched on, so that the substrates are first joined together only uniaxially along the contacting axis,
wherein the remaining fixing elements are thereafter switched off, so that the substrates are joined together over the whole area.